

General Description

The WSR7N65F is the highest performance trench N-Ch MOSFET with extreme high cell density, which provide excellent $R_{DS(on)}$ and gate charge for most of the synchronous buck converter applications.

The WSR7N65F meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent $C_{dv/dt}$ effect decline
- Green Device Available

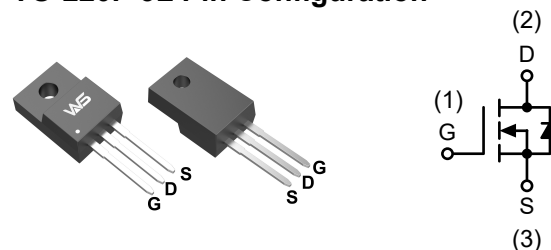
Product Summary

BV_{DSS}	$R_{DS(on)}$	I_D
650V	1000m Ω	7A

Applications

- AC/DC Power Conversion in Switched Mode Power Supplies (SMPS).
- Uninterruptible Power Supply(UPS)
- Adapter.

TO-220F-3L Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	650	V
V_{GS}	Gate-Source Voltage	± 30	V
$I_D@T_C=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^{1.5}$	7	A
$I_D@T_C=100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^{1.5}$	4	A
I_{DM}	Pulsed Drain Current ^{1,2,5}	28	A
EAS	Single Pulse Avalanche Energy ¹	171	mJ
P_D	Total Power Dissipation ^{1,5}	48	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient ¹	---	62.5	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	2.7	$^\circ C/W$

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	650	---	---	V
ΔBV _{DSS} /ΔT _J	BVDSS Temperature Coefficient	Reference to 25°C, I _D =250uA	---	0.6	---	V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V, I _D =3.5A	---	1000	1300	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	2.0	3.0	4.0	V
ΔV _{GS(th)}	V _{GS(th)} Temperature Coefficient		---	-4.57	---	mV/°C
I _{DSS}	Drain-Source Leakage Current	V _{DS} =650V, V _{GS} =0V, T _J =25°C	---	---	1	uA
		V _{DS} =520V, V _{GS} =0V, T _J =55°C	---	---	10	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±30V, V _{DS} =0V	---	---	±100	nA
g _{fs}	Forward Transconductance	V _{DS} =40V, I _D =3.5A	---	6	---	S
Q _g	Total Gate Charge (10V)	V _{DS} =520V, V _{GS} =10V, I _D =7A	---	16	---	nC
Q _{gs}	Gate-Source Charge		---	4	---	
Q _{gd}	Gate-Drain Charge		---	3.6	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =300V, V _{GS} =10V, R _G =25Ω, I _D =10A.	---	17	---	ns
T _r	Rise Time		---	26	---	
T _{d(off)}	Turn-Off Delay Time		---	23	---	
T _f	Fall Time		---	57	---	
C _{iss}	Input Capacitance	V _{DS} =25V, V _{GS} =0V, f=1MHz	---	930	---	pF
C _{oss}	Output Capacitance		---	100	---	
C _{rss}	Reverse Transfer Capacitance		---	4.5	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current ^{1,2,5}	V _G =V _D =0V, Force Current	---	---	7	A
I _{SM}	Pulsed Source Current ^{1,2}		---	---	28	A
V _{SD}	Diode Forward Voltage ¹	V _{GS} =0V, I _S =7A, T _J =25°C	---	---	1.4	V
t _{rr}	Reverse Recovery Time	I _F =7A, dI/dt=40A/μs, T _J =25°C	---	487	---	nS
Q _{rr}	Reverse Recovery Charge		---	2289	---	nC

Notes:

Note 1 : limited by maximum junction temperature.

Note 2 : Bond wire current limit.

Note 3 : V_{DS}=520V, I_D=7A.

Note 4 : I_D=0.5A, V_{DD}=50V, T_J=25°C.

Note 5 : Repetitive Rating : Pulse width limited by maximum junction temperature.

Typical Characteristics

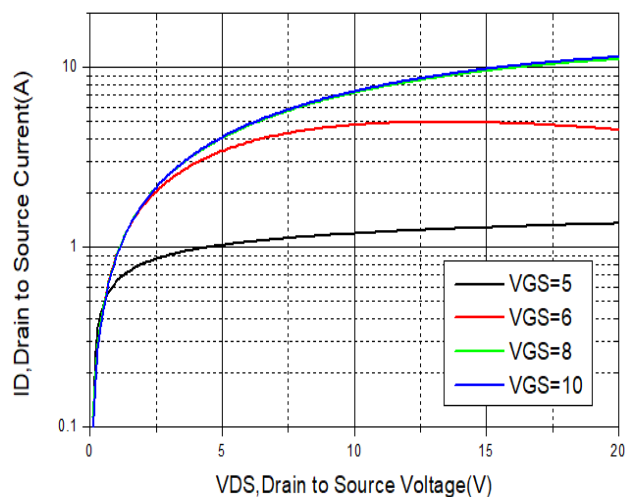


Figure 1 Output Characteristics

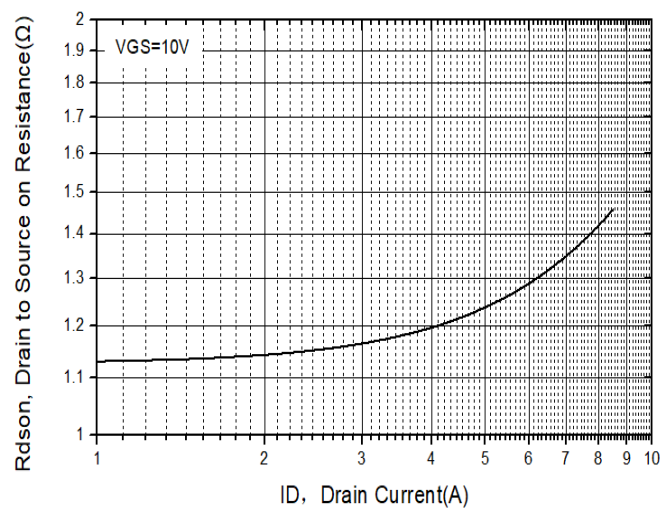


Figure 3 Rdson-ID Characteristics

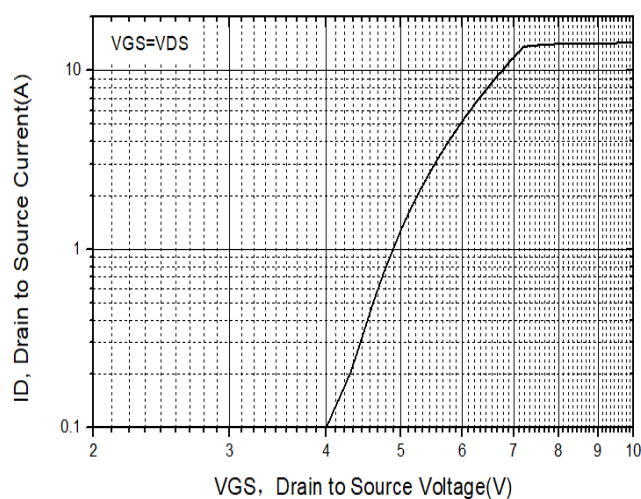


Figure 2 Transfer Characteristics

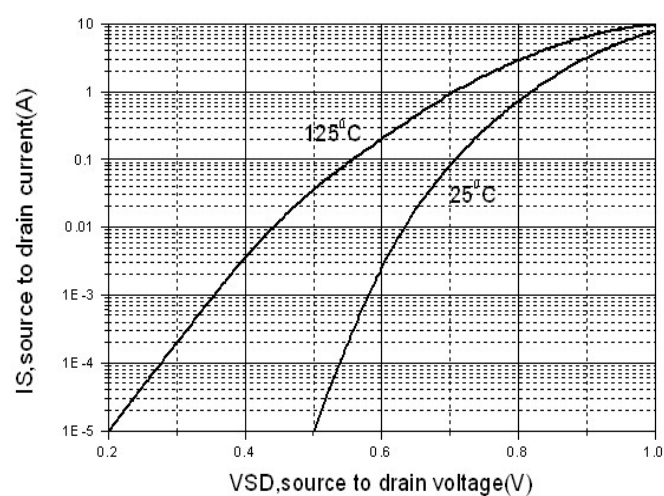


Figure 4 Body diode Characteristics

Typical Characteristics

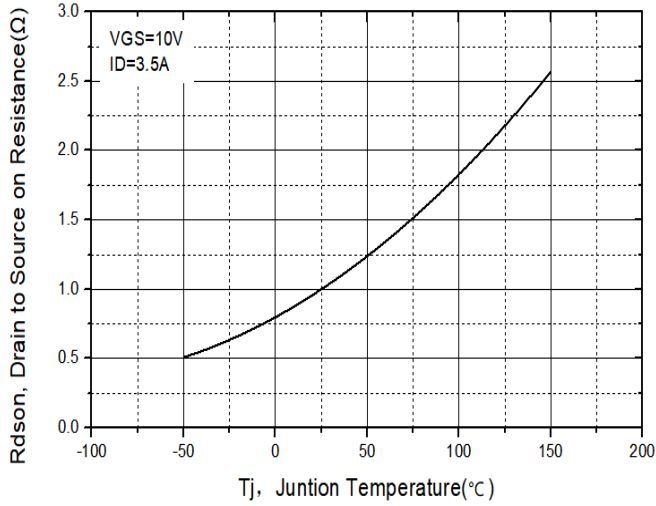


Figure 5 Rdson- Tj Relation

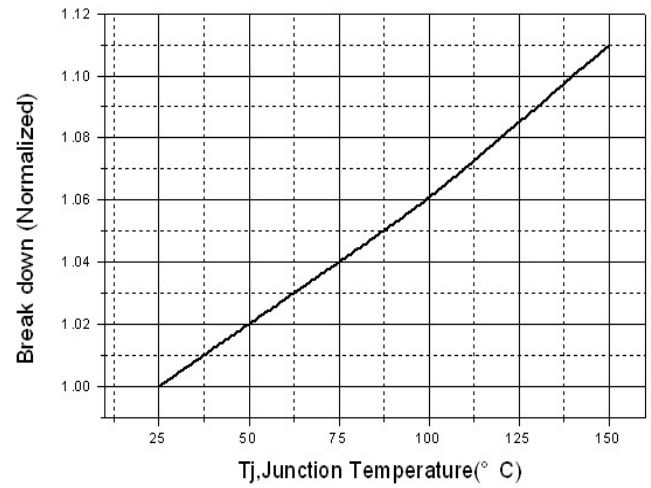


Figure 6 BVDSS vs Junction Temperature

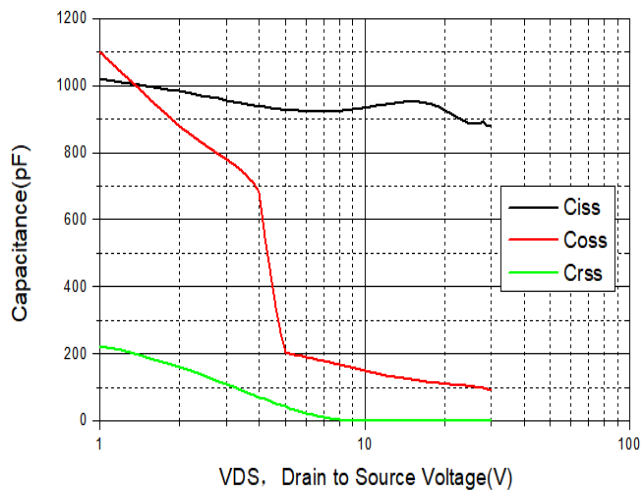


Figure 7 Capacitance vs Vds

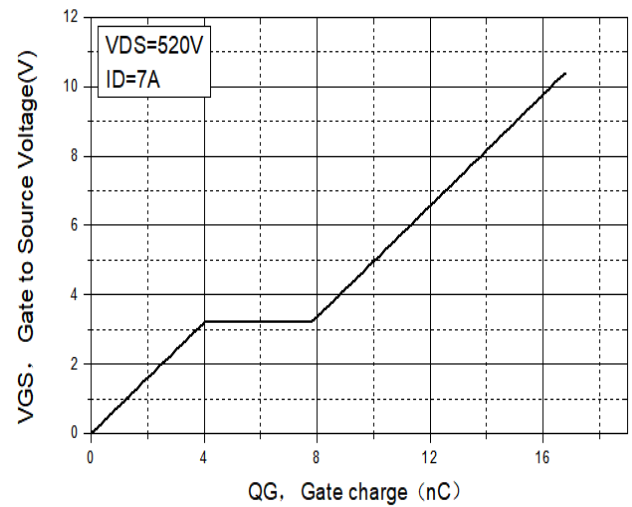


Figure 8 VGS vs QG Characteristics

Typical Characteristics

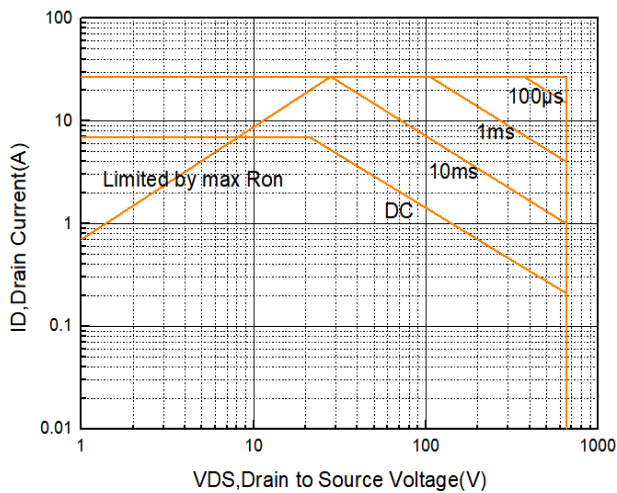


Figure 9 Safe Operation Area

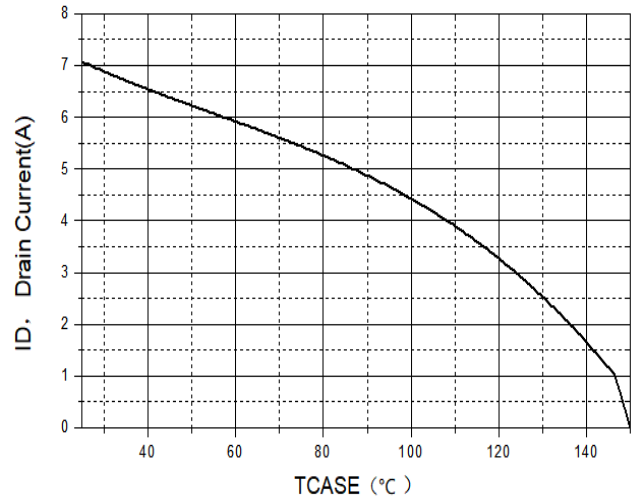


Figure 10 Maximum current attenuation

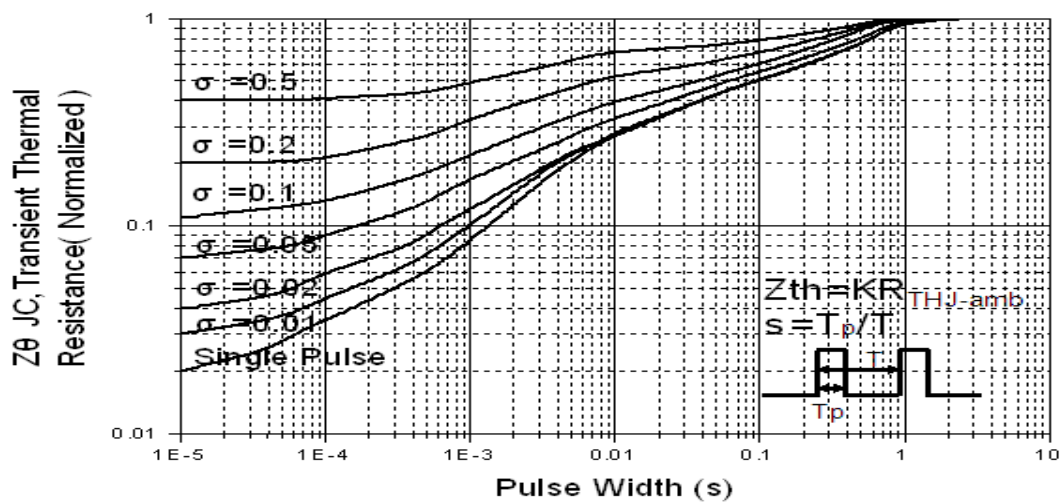
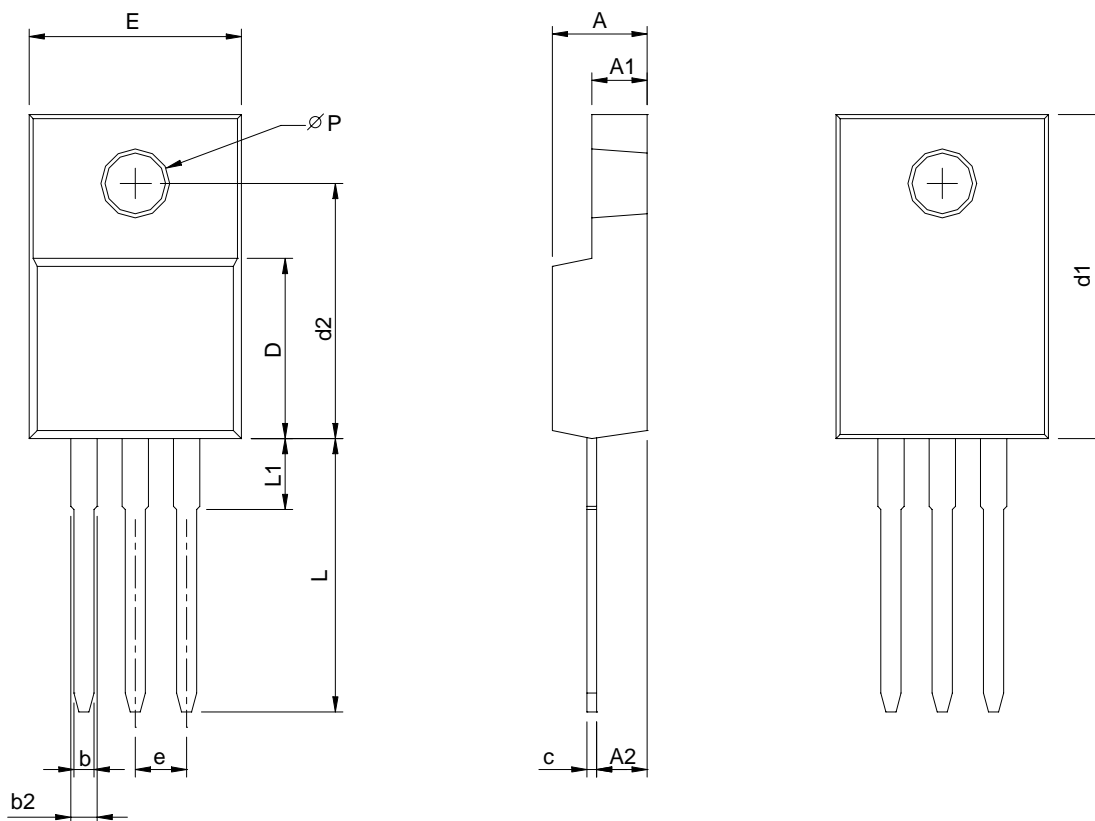


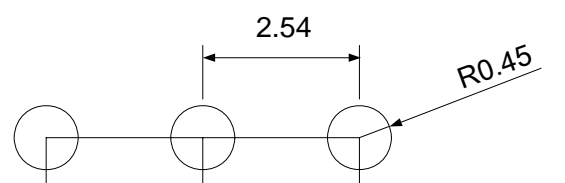
Figure 11 Normalized Maximum Transient Thermal Impedance

Packaging information



SYMBOL	TO-220F-3L			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.20	4.80	0.165	0.189
A1	2.34	3.20	0.092	0.126
A2	2.10	2.90	0.083	0.114
b	0.50	0.90	0.020	0.035
b2	0.91	1.90	0.035	0.075
c	0.30	0.80	0.012	0.031
D	8.10	9.40	0.319	0.370
d1	14.50	16.50	0.571	0.650
d2	12.10	12.90	0.476	0.508
E	9.70	10.70	0.382	0.421
e	2.54 BSC		0.100 BSC	
L	13.00	14.50	0.512	0.570
L1	1.60	4.00	0.063	0.157
P	3.00	3.60	0.118	0.142

RECOMMENDED LAND PATTERN



UNIT: mm

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